



## TGD P-Channel Enhancement Mode Power MOSFET

**Description**

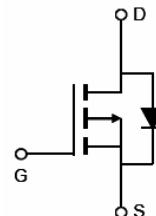
The TGD30P28Q uses advanced trench technology to provide excellent  $R_{DS(ON)}$ . This device is suitable for use as a load switch or power management.

**General Features**

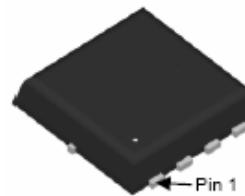
- $V_{DS} = -30V, I_D = -28A$
- $R_{DS(ON)} < 12m\Omega @ V_{GS} = -10V$
- $R_{DS(ON)} < 17m\Omega @ V_{GS} = -4.5V$
- High power and current handling capability
- Lead free product is acquired
- Surface mount package

**Application**

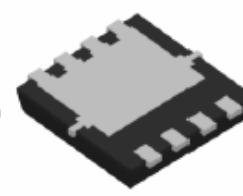
- Power management
- Load switch



Schematic diagram



Top View



Bottom View

**Package Marking and Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
30P28Q	30P28Q	DFN3.3X3.3-8L			

**Absolute Maximum Ratings ( $T_A=25^\circ C$  unless otherwise noted)**

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	-30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	-28	A
Drain Current-Pulsed <sup>(Note 1)</sup>	$I_{DM}$	-80	A
Maximum Power Dissipation	$P_D$	30	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	°C

**Thermal Characteristic**

Thermal Resistance, Junction-to-Case <sup>(Note 2)</sup>	$R_{\theta JC}$	4.17	°C/W
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**Electrical Characteristics ( $T_A=25^\circ C$  unless otherwise noted)**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-30	-	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=-30V, V_{GS}=0V$	-	-	-1	$\mu A$

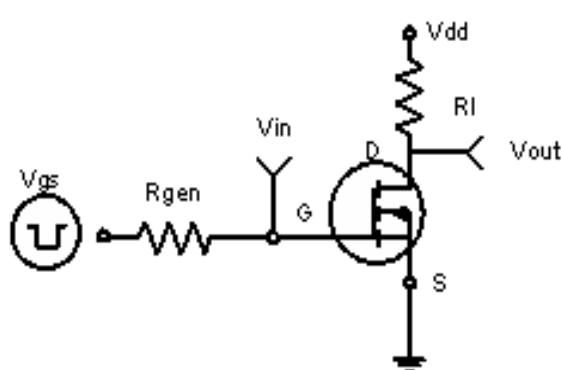


Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
<b>On Characteristics</b> <small>(Note 3)</small>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-0.8	-1.3	-2.0	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-20A	-	9.9	12	mΩ
	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-20A	-	13.4	17	
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =-10V, I <sub>D</sub> =-20A	-	25	-	S
<b>Dynamic Characteristics</b> <small>(Note 4)</small>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =-15V, V <sub>GS</sub> =0V, F=1.0MHz	-	2060	-	PF
Output Capacitance	C <sub>oss</sub>		-	370	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	295	-	PF
<b>Switching Characteristics</b> <small>(Note 4)</small>						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =-15V, I <sub>D</sub> =-20A, V <sub>GS</sub> =-10V, R <sub>GEN</sub> =3Ω	-	11	-	nS
Turn-on Rise Time	t <sub>r</sub>		-	9.4	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	24	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	12	-	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =-15V, I <sub>D</sub> =-20A, V <sub>GS</sub> =-10V	-	30	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	4.5	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	9.5	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage <small>(Note 3)</small>	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =-28A	-	-	-1.2	V

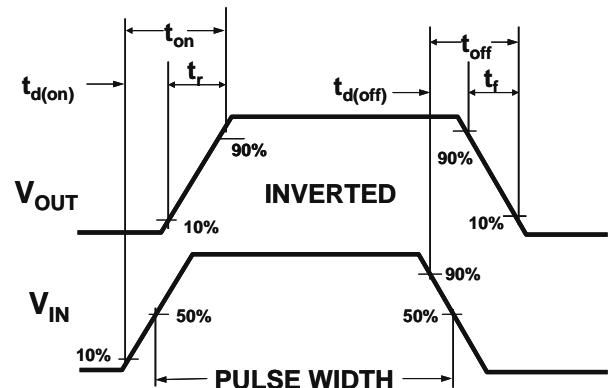
**Notes**

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production

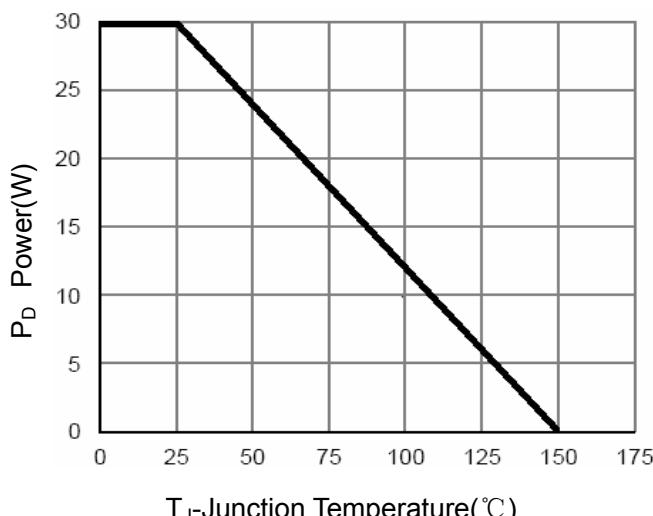
### Typical Electrical and Thermal Characteristics



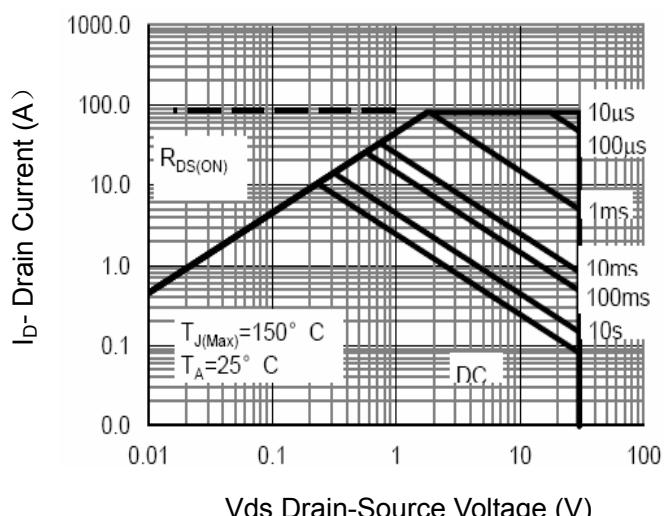
**Figure 1** Switching Test Circuit



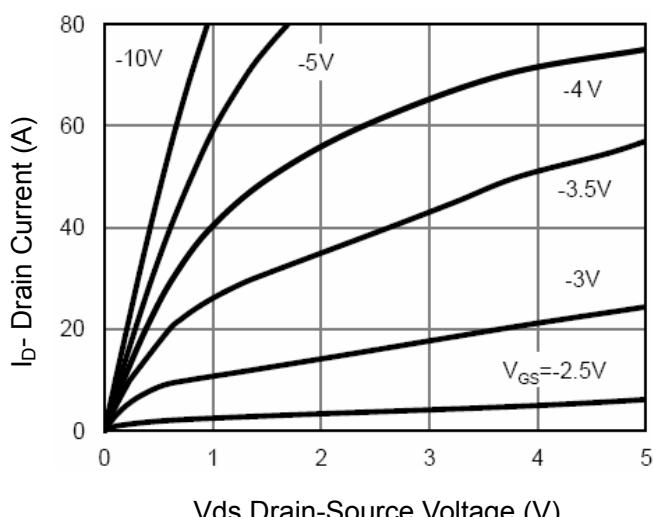
**Figure 2** Switching Waveforms



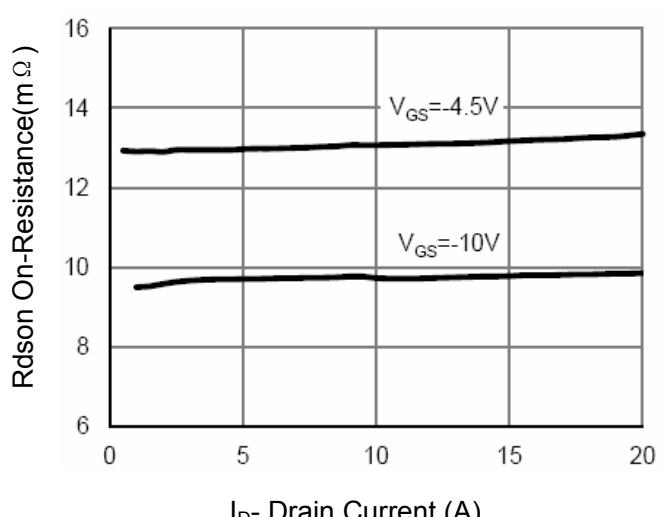
**Figure 3** Power Dissipation



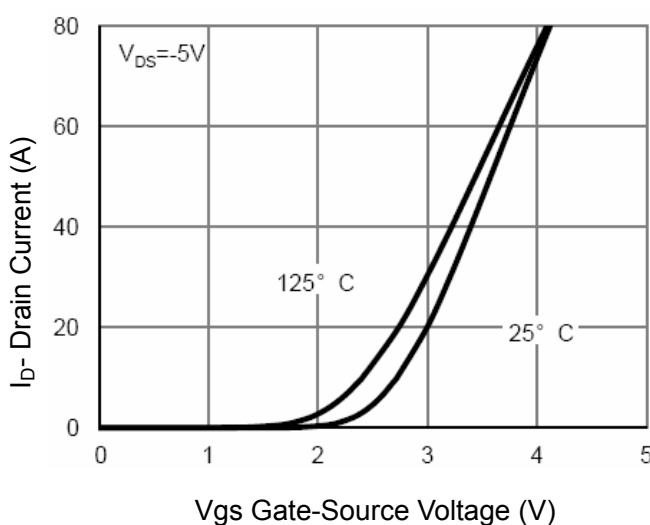
**Figure 4** Safe Operation Area



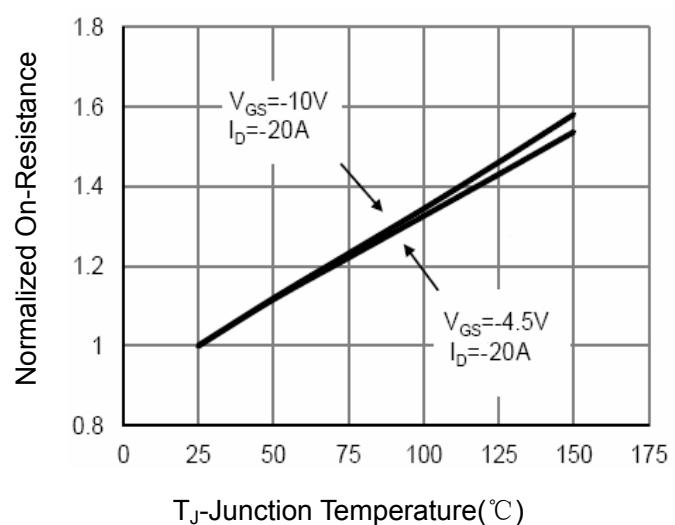
**Figure 5** Output Characteristics



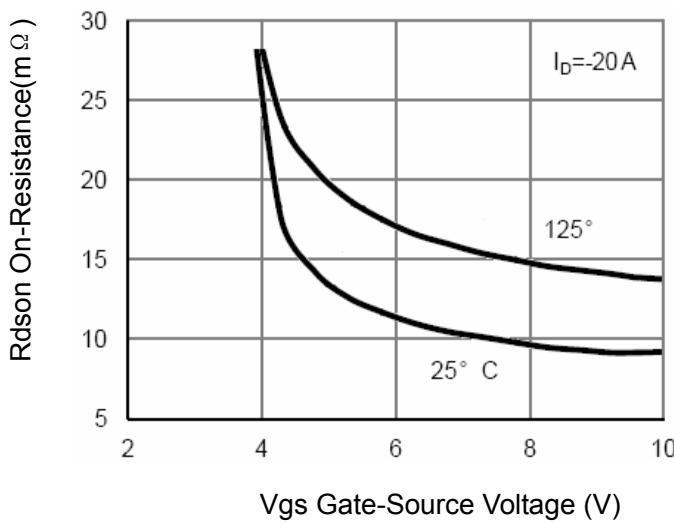
**Figure 6** Drain-Source On-Resistance



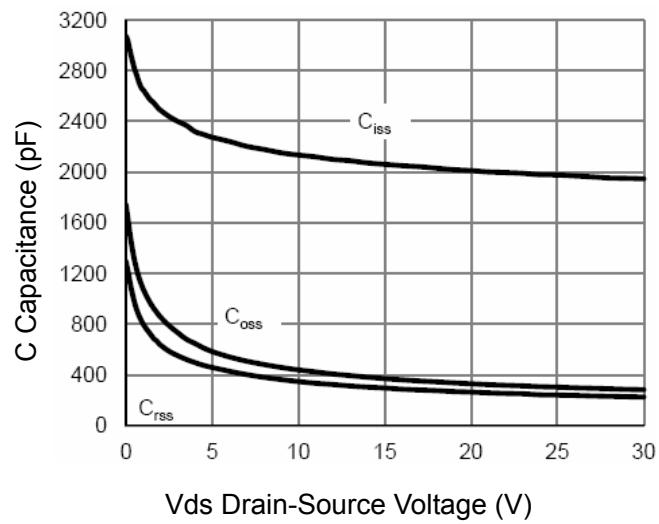
**Figure 7 Transfer Characteristics**



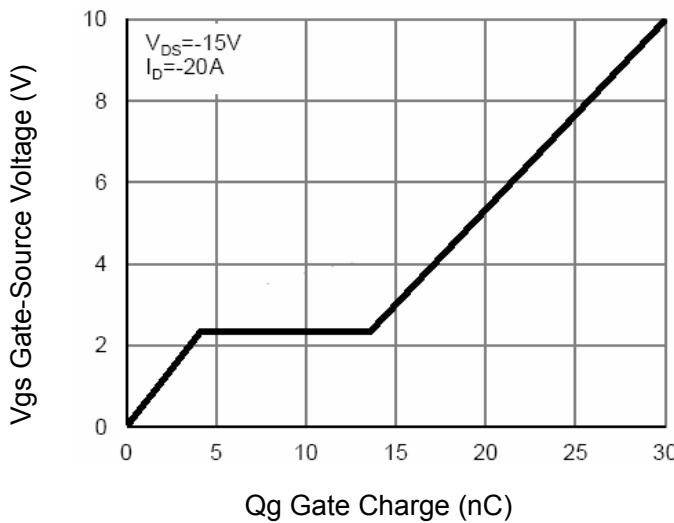
**Figure 8 Drain-Source On-Resistance**



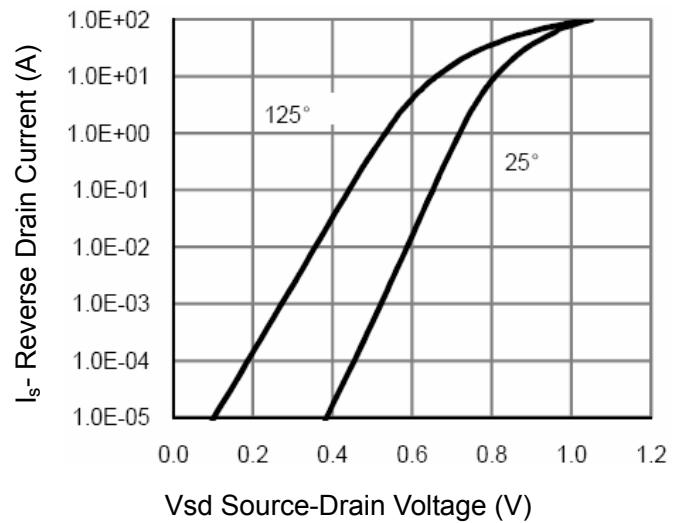
**Figure 9  $R_{DS(on)}$  vs  $V_{GS}$**



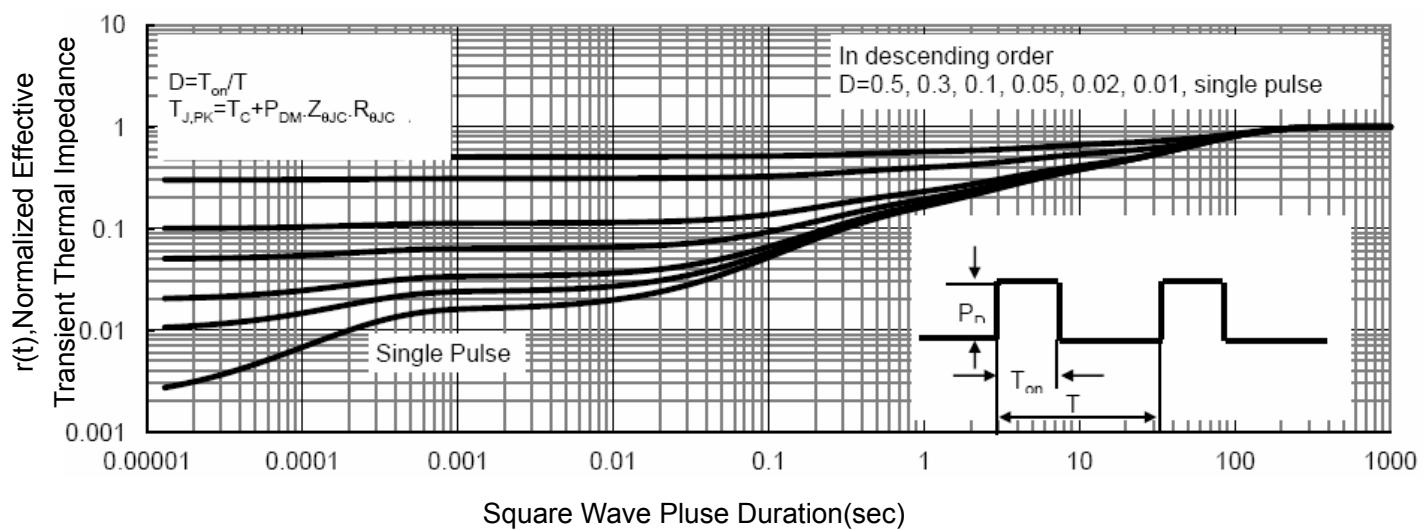
**Figure 10 Capacitance vs  $V_{DS}$**



**Figure 11 Gate Charge**



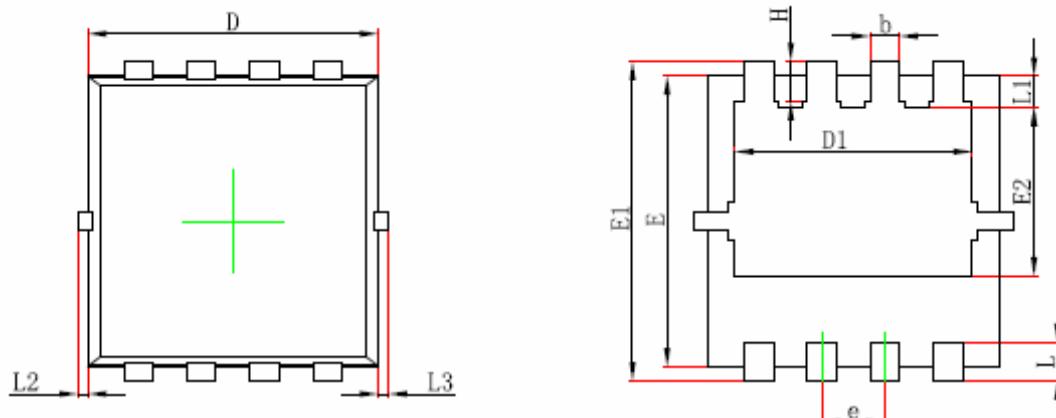
**Figure 12 Source-Drain Diode Forward**



**Figure 13 Normalized Maximum Transient Thermal Impedance**

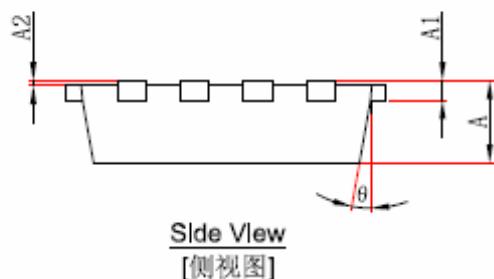


## DFN3.3X3.3-8L Package Information



Top View  
[顶视图]

Bottom View  
[背视图]



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.650	0.850	0.026	0.033
A1	0.152 REF.		0.006 REF.	
A2	0~0.05		0~0.002	
D	2.900	3.100	0.114	0.122
D1	2.300	2.600	0.091	0.102
E	2.900	3.100	0.114	0.122
E1	3.150	3.450	0.124	0.136
E2	1.535	1.935	0.060	0.076
b	0.200	0.400	0.008	0.016
e	0.550	0.750	0.022	0.030
L	0.300	0.500	0.012	0.020
L1	0.180	0.480	0.007	0.019
L2	0~0.100		0~0.004	
L3	0~0.100		0~0.004	
H	0.315	0.515	0.012	0.020
θ	9°	13°	9°	13°